UNITED STATES DEPARTMENT OF COMMERCE United States Patent and Trademark Office Address: COMMISSIONER FOR PATENTS P.O. Box 1450 Alexandria, Virginia 22313-1450 www.uspto.gov

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/573,467	04/13/2007	Hiroya Kobayashi	46884-5465	9269	
	7590 12/09/200 DDLE & REATH (DC)	=	EXAM	IINER	
1500 K STREE			PATTON, PAUL E		
SUITE 1100 WASHINGTO	N, DC 20005-1209		ART UNIT	PAPER NUMBER	
			2822	2822	
			MAIL DATE	DELIVERY MODE	
			12/09/2008	PAPER	

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

	Application No.	Applicant(s)	
	10/573,467	KOBAYASHI ET AL.	
Office Action Summary	Examiner	Art Unit	
	PAUL E. PATTON	2822	
The MAILING DATE of this communication Period for Reply	appears on the cover sheet w	ith the correspondence address	
A SHORTENED STATUTORY PERIOD FOR RE WHICHEVER IS LONGER, FROM THE MAILING - Extensions of time may be available under the provisions of 37 CFI after SIX (6) MONTHS from the mailing date of this communication - If NO period for reply is specified above, the maximum statutory pe - Failure to reply within the set or extended period for reply will, by st Any reply received by the Office later than three months after the meaned patent term adjustment. See 37 CFR 1.704(b).	G DATE OF THIS COMMUNI R 1.136(a). In no event, however, may a . riod will apply and will expire SIX (6) MOI atute, cause the application to become Al	CATION. reply be timely filed NTHS from the mailing date of this communic BANDONED (35 U.S.C. § 133).	
Status			
1) Responsive to communication(s) filed on 1	This action is non-final. wance except for formal mat	·	s is
Disposition of Claims			
4) ☐ Claim(s) is/are pending in the applic 4a) Of the above claim(s) is/are with 5) ☐ Claim(s) is/are allowed. 6) ☒ Claim(s) <u>1-3</u> is/are rejected. 7) ☐ Claim(s) is/are objected to. 8) ☐ Claim(s) are subject to restriction an	drawn from consideration.		
9)☐ The specification is objected to by the Exam	niner		
10) The drawing(s) filed on is/are: a) Applicant may not request that any objection to Replacement drawing sheet(s) including the cor	accepted or b) objected to the drawing(s) be held in abeyal rection is required if the drawing	nce. See 37 CFR 1.85(a). (s) is objected to. See 37 CFR 1.12	` '
Priority under 35 U.S.C. § 119			
12) Acknowledgment is made of a claim for fore a) All b) Some * c) None of: 1. Certified copies of the priority document of: 2. Certified copies of the priority document of: 3. Copies of the certified copies of the priority document of the pr	nents have been received. Hents have been received in A Poriority documents have beer Treau (PCT Rule 17.2(a)).	Application No received in this National Stage	
Attachment(s) 1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO/SB/08) Paper No(s)/Mail Date 9/08/08, 9/19/08, 10/07/08.	Paper No(Summary (PTO-413) s)/Mail Date nformal Patent Application 	

Art Unit: 2822

DETAILED ACTION

Response to Arguments

- 1. Applicant's arguments filed September 19, 2008 have been fully considered but they are not persuasive. In particular applicant argues that neither Higashi nor Saito disclose a thinned portion. However, it is evident that the thinned portion is clearly disclosed by the primary reference to Muramatsu (US 2002.0020859), who discloses a virtually identical device to that of the applicant differing only in the details of the resin application and the gap. Higashi provides the teaching of the pre-formed resin sheet and Saito teaches allowing a gap in the material to allow ingress or egress of material. The role of the secondary references is to establish that these techniques of device attachment are, indeed, well known in the art and therefore obvious to one of ordinary skill in the relevant technology. The reference to the thinned portion is clearly to that of Muramatsu. Further changing the term of a gap to a communication portion does not materially alter the meaning of the claim nor alter the basis of rejection.
- 2. In response to applicant's argument that the references fail to show certain features of applicant's invention, it is noted that the features upon which applicant relies (i.e., avoiding cracking of the thinned portion, and distortion due to trapped air) are not recited in the rejected claim(s). Although the claims are interpreted in light of the specification, limitations from the specification are not read into the claims. See *In re Van Geuns*, 988 F.2d 1181, 26 USPQ2d 1057 (Fed. Cir. 1993).

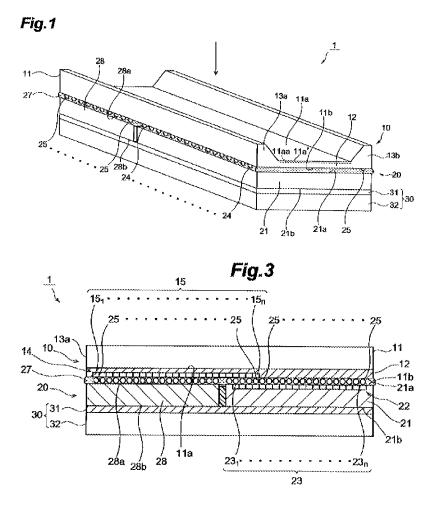
Art Unit: 2822

Claim Rejections - 35 USC § 103

3. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

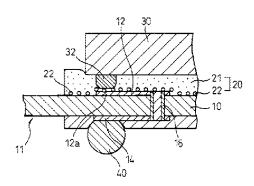
(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

- 4. Claims 1-3 are rejected under 35 U.S.C. 103(a) as being unpatentable over Muramatsu (US 2002/00220859 A1) in view of Higashi et al., (USPAT 5,918,113) hereinafter Higashi and further in view of Saito (JP2003-124259).
- 5. As to claims 1 and 3, Muramatsu discloses and shows (Figs 1 & 3) a semiconductor 13b having a photodetecting unit (11) formed on one surface, a thinned portion formed by etching a region, opposing a photodetecting unit, of another surface, an outer edge surrounding the thinned portion, and first electrodes disposed on the one surface the outer edge and electrically connected to the photodetecting unit; a wiring substrate (21) disposed to oppose the one surface side of the semiconductor substrate and having second electrodes (23) connected via conductive bumps (25) to the first electrodes; and a resin (27), filling a gap between the wiring substrate and the outer edge with the conductive. bumps.



- 6. Muramatsu does not disclose or show that the resin is a resin sheet, adhering the sheet to a predetermined region on the other surface of the substrate and thermocompression bonding the semiconductor substrate with the resin sheet to the wiring substrate.
- 7. Higashi discloses and shows (Higashi, Fig 1) the resin is a resin sheet, adhering the sheet to a predetermined region on the other surface of the substrate and thermocompression bonding the semiconductor substrate with the resin sheet to the wiring substrate. (Column 3, line 37 column 4, line 43, see also the entire patent).

Fig.1



- 8. Higashi is evidence that a person of ordinary skill in the art would find a reason, suggestion or motivation to use a resin sheet, adhering the sheet to a predetermined region on the other surface of the substrate and thermo-compression bonding the semiconductor substrate with the resin sheet to the wiring substrate.
- 9. Therefore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Muramatsu by using a resin sheet, adhering the sheet to a predetermined region on the other surface of the substrate and thermocompression bonding the semiconductor substrate with the resin sheet to the wiring substrate for advantages such as simplifying the assembly process with improved production efficiency according to the teachings of Higashi (Column 1, lines 49-53).
- 10. Muramatsu as modified by Higashi does not disclose that the resin sheet surrounds the periphery of the gap between the wiring substrate and the outer edge of the thinned portion of the device except for portion of the periphery.
- 11. Saito, discloses and shows (Fig 4) a resin sheet (30) with a communicating portion formed so as to laterally penetrate through the resin sheet.

Art Unit: 2822

12. Saito is evidence that a person of ordinary skill in the art would find a reason, suggestion or motivation to use a resin sheet with a communicating portion formed so as to laterally penetrate through the resin sheet.

- 13. Therefore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Muramatsu as modified by Higashi by using a resin sheet with a communicating portion formed so as to laterally penetrate through the resin sheet. for advantages such as permitting the ingress or egress of materials filling the gap according to the teachings of Saito..
- 14. As to claim 2, Muramatsu discloses the photodetecting unit has a plurality of pixels (15) that are arrayed one-dimensionally or two-dimensionally.

Conclusion

15. **THIS ACTION IS MADE FINAL.** Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

Art Unit: 2822

Any inquiry concerning this communication or earlier communications from the examiner should be directed to PAUL E. PATTON whose telephone number is (571)272-9762. The examiner can normally be reached on 7:00 - 5:30 Monday through Thursday.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Zandra Smith can be reached on 571-272-2429. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

/Zandra V. Smith/ Supervisory Patent Examiner, Art Unit 2822 Paul E Patton Examiner Art Unit 2822

/P. E. P./ Examiner, Art Unit 2822